

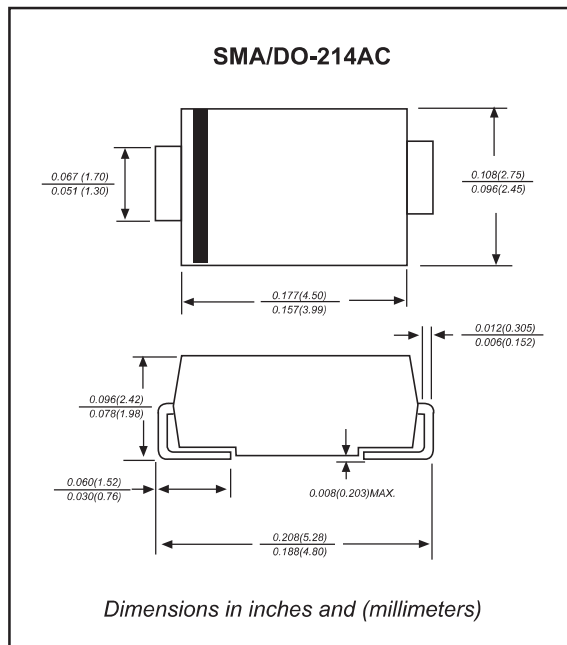
Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Metal silicon junction, majority carrier conduction
- ◆ Low power loss, high efficiency
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed:
250°C/10 seconds at terminals
- ◆ Compliant to RoHS Directive 2011/65/EU

Mechanical data

- ◆ **Case:** JEDEC DO-214AC molded plastic body
- ◆ **Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- ◆ **Polarity:** Color band denotes cathode end
- ◆ **Mounting Position:** Any

Package outline



Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	SYMBOL	SSA34	UNIT
Maximum repetitive peak reverse voltage	V_{RRM}	40	V
Maximum RMS voltage	V_{RMS}	28	V
Maximum DC blocking voltage	V_{DC}	40	V
Maximum average forward rectified current at T_L (fig. 1)	$I_{F(AV)}$	3.0	A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I_{FSM}	75	A
Voltage rate of change (rated V_R)	dV/dt	10 000	V/ μs
Operating junction temperature range	T_J	-65 to +150	$^\circ\text{C}$
Storage temperature range	T_{STG}	-65 to +150	$^\circ\text{C}$

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

PARAMETER	TEST CONDITIONS		SYMBOL	SSA34		UNIT
				TYP.	MAX.	
Maximum instantaneous forward voltage ⁽¹⁾	3.0 A	$T_J = 25^\circ\text{C}$	V_F	0.46	0.49	V
		$T_J = 125^\circ\text{C}$		0.38	0.42	
Maximum reverse current at rated V_R ⁽²⁾		$T_J = 25^\circ\text{C}$	I_R	-	0.2	mA
		$T_J = 125^\circ\text{C}$		17	30	

Notes

- (1) Pulse test: 300 μs pulse width, 1 % duty cycle
(2) Pulse test: Pulse width ≤ 40 ms

THERMAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

PARAMETER	SYMBOL	SSA34	UNIT
Typical thermal resistance ⁽¹⁾	$R_{\theta JA}$	110	$^\circ\text{C/W}$
	$R_{\theta JL}$	28	

Note

- (1) Aluminum substrate mounted

Rating and characteristic curves

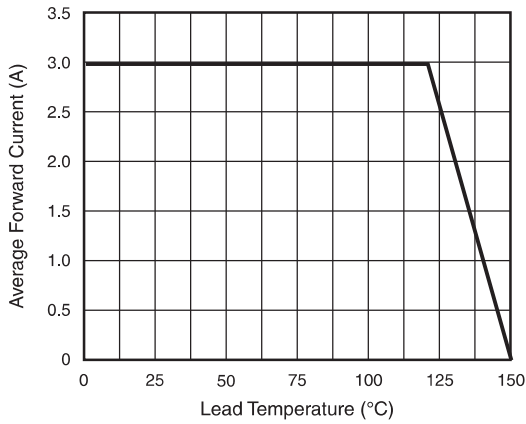


Fig. 1 - Forward Current Derating Curve

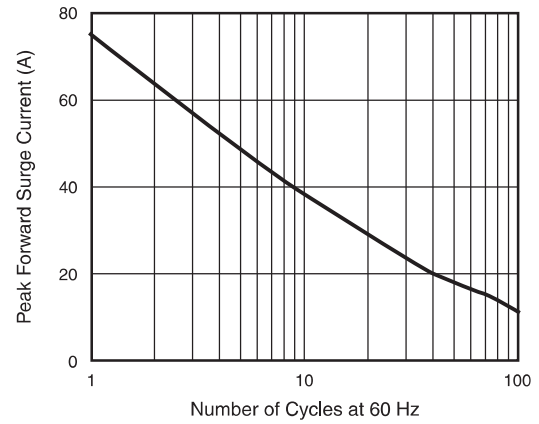


Fig. 2 - Maximum Non-Repetitive Peak Forward Surge Current

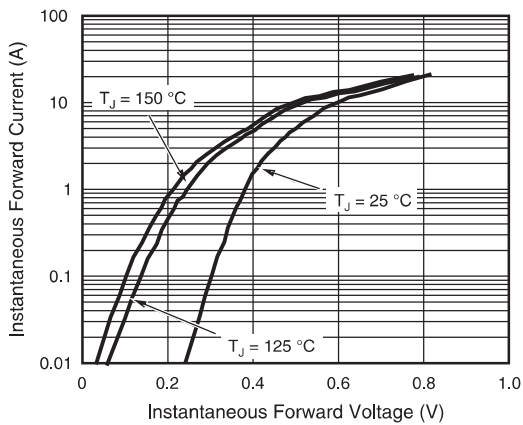


Fig. 3 - Typical Instantaneous Forward Characteristics

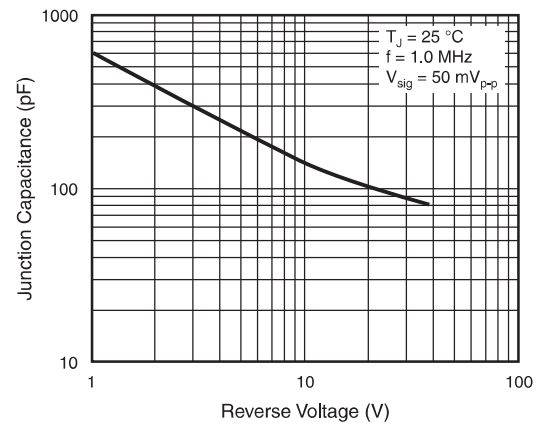


Fig. 5 - Typical Junction Capacitance

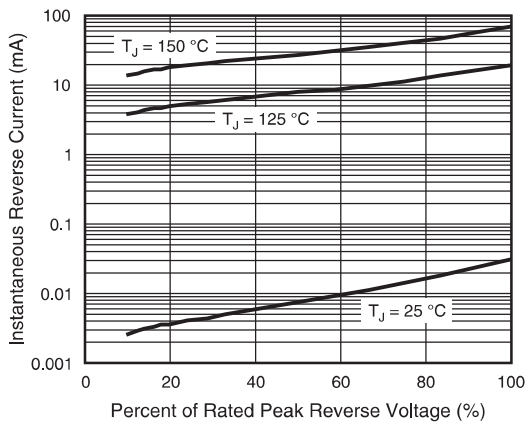


Fig. 4 - Typical Reverse Characteristics

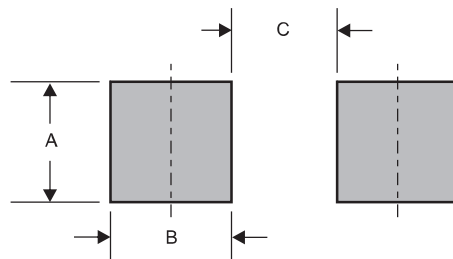
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
SSA34	A34

Suggested solder pad layout

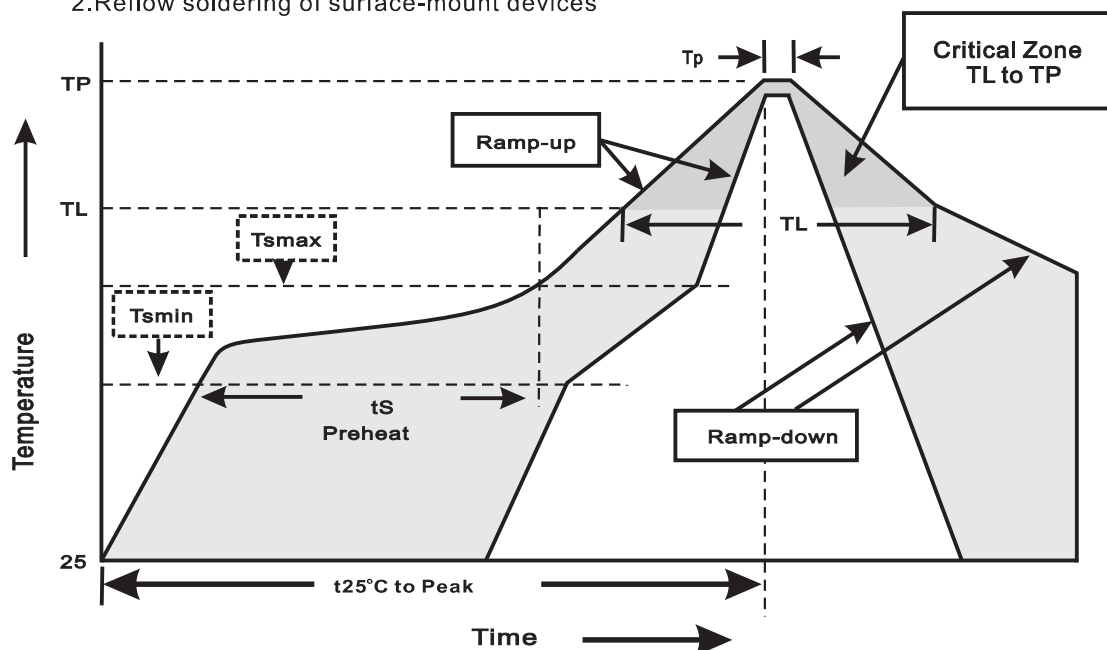


Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMA	0.110 (2.80)	0.063 (1.60)	0.087 (2.20)

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T_L to T_P)	$<3^{\circ}\text{C}/\text{sec}$
Preheat -Temperature Min(T_{min}) -Temperature Max(T_{max}) -Time(min to max)(t_s)	150°C 200°C $60\sim 120\text{sec}$
T_{max} to T_L -Ramp-upRate	$<3^{\circ}\text{C}/\text{sec}$
Time maintained above: -Temperature(T_L) -Time(t_L)	217°C $60\sim 260\text{sec}$
Peak Temperature(T_P)	$255^{\circ}\text{C}-0/+5^{\circ}\text{C}$
Time within 5°C of actual Peak Temperature(t_P)	$10\sim 30\text{sec}$
Ramp-down Rate	$<6^{\circ}\text{C}/\text{sec}$
Time 25°C to Peak Temperature	$<6\text{minutes}$